

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled PRESSURE SENSITIVE ADHESIVE ARTICLES, the specification of which:

X is attached hereto.

 was filed on as Application Serial No.

 and was amended on (if applicable).

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, § 1.56(a).

I hereby claim foreign priority benefits under Title 35, United States Code, § 119(a)-(d) foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

<u>Prior Foreign Application(s)</u>			<u>Priority Claimed</u>	
<u>2002-252156</u>	<u>Japan</u>	<u>29/August/2002</u>	<u>X</u>	<u> </u>
(Number)	(Country)	(Day/Month/Year Filed)	Yes	No

I hereby claim the benefit under Title 35, United States Code, § 119(e) of any United States provision(s) listed below:

 (Application Serial No.) (Filing Date)

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, § 1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

 (Application Serial No.) (Filing Date) (Status-patented, pending, abandoned)

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Inventor's Signature
Full name of sole or first inventor
Residence
Citizenship
Post Office Address

Isao Sakurai Date 18/August/2003
Isao SAKURAI
Saitama, Japan
Japan

Inventor's Signature
Full name of second joint inventor, if any
Residence
Citizenship
Post Office Address

c/o LINTEC Corporation, 23-23, Hon-cho,
Itabashi-ku, Tokyo 173-0001 Japan
Tomishi Shibano Date 18/August/2003
Tomishi SHIBANO
Saitama, Japan
Japan
c/o LINTEC Corporation, 23-23, Hon-cho,
Itabashi-ku, Tokyo 173-0001 Japan

Inventor(s): Isao SAKURAI, Tomishi SHIBANOTitle: PRESSURE SENSITIVE ADHESIVE ARTICLES**POWER OF ATTORNEY**

The specification of the above-identified patent application:



is attached hereto



was filed on _____ as application Serial No. _____

I hereby revoke all previously granted powers of attorney in the above-identified patent application and appoint the following attorneys to prosecute said patent application and to transact all business in the Patent and Trademark Office connected therewith:

G. Peter NICHOLS Reg. No. 34,401
 Tadashi HORIE Reg. No. 40,437
 Gregory H. ZAYLA Reg. No. 48,059

Please address all correspondence and telephone calls to _____ in care of:

BRINKS HOFER GILSON & LIONE
 P.O. BOX 10395
 CHICAGO, ILLINOIS 60610
 (312) 321-4200

The undersigned hereby authorizes the U.S. attorneys named herein to accept and follow instructions from _____ as to any action to be taken in the Patent and Trademark Office regarding this application without direct communication between the U.S. attorney and the undersigned. In the event of a change in the persons from whom instructions may be taken, the U.S. attorneys named herein will be so notified by the undersigned.

LINTEC Corporation, a Japanese Corporation

(Name of Assignee)

(Type of Assignee, e.g., corporation, partnership, university, government agency, etc.)

certifies that it is the assignee of the entire right, title and interest in the patent application identified above by virtue of either:

A. ☒ An assignment from the inventor(s) of the patent application identified above, a copy of which is attached hereto.

OR

B. ☐ An assignment from the inventor(s) of the patent application identified above. The assignment was recorded in the Patent and Trademark Office at Reel _____, Frame _____.
ORC. ☐ A chain of title from the inventor(s) of the patent application identified above, to the current assignee as shown below:

1. From: _____ To: _____
 The document was recorded in the Patent and Trademark Office at
 Reel _____, Frame _____, or a copy thereof is attached.

2. From: _____ To: _____
 The document was recorded in the Patent and Trademark Office at
 Reel _____, Frame _____, or a copy thereof is attached.



Additional documents in the chain of title are listed on a supplemental sheet.

The undersigned has reviewed the assignment or all the documents in the chain of title of the patent application identified above and, to the best of undersigned's knowledge and belief, title is in the assignee identified above.

The undersigned (whose title is supplied below) is empowered to act on behalf of the assignee.

I hereby declare that all statements made herein of my own knowledge are true, and that all statements made on information and belief are believed to be true; and further, that these statements are made with the knowledge that willful false statements, and the like so made, are punishable by fine or imprisonment, or both, under Section 1001, Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Name: Kyohei TANAKATitle: PresidentSignature: K. TanakaDate: August 20, 2003